

Product Change Notification / LIAL-31KIYP880

Date:			

20-Jan-2022

Product Category:

SONET/SDH/T1/E1 Devices

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4700.001 Final Notice: Qualification of ATK as an additional assembly site for PM5336B-FEI and PM5334A-FEI Microsemi catalog part numbers (CPN) available in 1152L BBGA (35x35x3.32mm) package using E705G substrate core material.

Affected CPNs:

LIAL-31KIYP880_Affected_CPN_01202022.pdf LIAL-31KIYP880_Affected_CPN_01202022.csv

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of ATK as an additional assembly site for PM5336B-FEI and PM5334A-FEI Microsemi catalog part numbers (CPN) available in 1152L BBGA (35x35x3.32mm) package using E705G substrate core material.

Pre and Post Change Summary:

	Pre Change	Post Change					
Assembly Site	STATS CHIPPAC KOREA LTD.	STATS CHIPPAC KOREA LTD.	Amkor Technology Korea (K4), INC.				
Assembly site	(STAK)	(STAK)	(ATK)				
Bump material	Sn1.8Ag	Sn1.8Ag Sn1.8Ag					
Die attach material	WF3617	WF3617	SCF5				
Underfill material	U8410-73C	U8410-73C	NAU-27-1F				
Substrate core material	E679FGR	E679FGR	E705G				
SM Material	AUS703	AUS703	AUS703				
Solder ball material	SAC305	SAC305	SAC305				
Solder ball flux	WF6063M5	WF6063M5	SCF-3				
Thermal Grease	SE4450	SE4450	DCL-5				
Heat spreader	R011-0197X	R011-0197X	101334109				

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying ATK as an additional assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:October 30, 2021 (date code: 2144)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2021							Octo	ber 2	2021			Janı	uary 2	022	
Workweek	23	24	25	26	27		40	41	42	43	44	02	03	04	05	06
Initial PCN Issue Date			Χ													
Qual Report Availability														Χ		

Final PCN Issue Date				Х					
Estimated									
Implementation						Χ			
Date									

Method to Identify Change:

Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

June 15, 2021: Issued initial notification.

July 02, 2021: Re-issued initial notification to update notification subject and description of change. **October 7, 2021:** Issued Final notification. Provided estimated first ship date to be on October 30, 2021.

January 20, 2022: Re-issued Final notification. Attached the qualification report.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-31KIYP880_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile, including opt out,</u> please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)
PM5336B-FEI PM5334A-FEI
PWIJSJ4A-FEI
Date: Wednesday, January 19, 2022